Product End-of-Life Disassembly Instructions

Product Category: Personal Computers

Marketing Name / Model
[List multiple models if applicable.]

HP ProDesk 405 G2 MT Business PC

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.
1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

<table>
<thead>
<tr>
<th>Item Description</th>
<th>Notes</th>
<th>Quantity of items included in product</th>
</tr>
</thead>
<tbody>
<tr>
<td>Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)</td>
<td>With a surface greater than 10 sq cm</td>
<td>2</td>
</tr>
<tr>
<td>Batteries</td>
<td>All types including standard alkaline and lithium coin or button style batteries</td>
<td>1</td>
</tr>
<tr>
<td>Mercury-containing components</td>
<td>For example, mercury in lamps, display backlights, scanner lamps, switches, batteries</td>
<td></td>
</tr>
<tr>
<td>Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm</td>
<td>Includes background illuminated displays with gas discharge lamps</td>
<td></td>
</tr>
<tr>
<td>Cathode Ray Tubes (CRT)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Capacitors / condensers (Containing PCB/PCT)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height</td>
<td>6</td>
<td></td>
</tr>
<tr>
<td>External electrical cables and cords</td>
<td>Power cord</td>
<td>1</td>
</tr>
<tr>
<td>Gas Discharge Lamps</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Plastics containing Brominated Flame Retardants weighing &gt; 25 grams (not including PCBs or PCAs already listed as a separate item above)</td>
<td>Cooler fan 84g, system fan 92g, PSU fan 63.5g</td>
<td>239.5g</td>
</tr>
<tr>
<td>Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner</td>
<td>Include the cartridges, print heads, tubes, vent chambers, and service stations.</td>
<td></td>
</tr>
<tr>
<td>Components and waste containing asbestos</td>
<td></td>
<td></td>
</tr>
</tbody>
</table>
Components, parts and materials containing refractory ceramic fibers
Components, parts and materials containing radioactive substances

2.0 Tools Required
List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

<table>
<thead>
<tr>
<th>Tool Description</th>
<th>Tool Size (if applicable)</th>
</tr>
</thead>
<tbody>
<tr>
<td>Screw driver</td>
<td>T-15</td>
</tr>
<tr>
<td>Micro shear</td>
<td>YN-3</td>
</tr>
<tr>
<td>Screw driver</td>
<td>PH2</td>
</tr>
<tr>
<td>Description #4</td>
<td></td>
</tr>
<tr>
<td>Description #5</td>
<td></td>
</tr>
</tbody>
</table>

3.0 Product Disassembly Process
3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Remove access panel. (see Figure 1-2)
2. Remove front bezel. (see Figure 3)
3. Remove the HDD (see Figure 4-6)
4. Remove the Slim ODD (see Figure 7-8)
5. Unplug all cable conn. from PCA. (see Figure 9)
6. Remove the PCA (see Figure 10-11)
7. Remove the DIMM. (see Figure 12)
8. Disconnect cooler cable then remove the cooler from board. (see Figure 13-14)
9. Remove the Battery. (see Figure 15)
10. Remove the FIO module from chassis. (see Figure 16-17)
11. Remove the SD card reader from chassis. (see Figure 18-19)
12. Remove the speaker from chassis. (see Figure 20-21)
13. Remove the PSU from chassis. (see Figure 22-23)
14. Remove the PSU chassis and remove the PSU board. (see Figure 24-34)
15. Remove the Electrolytic Capacitors from PSU board. (see Figure 35-41)

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).
Figure 1: Release Thumb screw on the access panel.

Figure 2: Gripping the tab at the end of access panel, pull towards the rear and remove from unit.

Figure 3: Pull 3 pcs bezel hooks and remove the front bezel from chassis.

Figure 4: Disconnect the SATA and power cables from HDD.

Figure 5: Release the HDD screws.

Figure 6: Remove the HDD from chassis.

PSG instructions for this template are available at EL-MF877-01.
| Figure 7 | Push the latch and release the Slim ODD. |
| Figure 8 | Remove the Slim ODD from chassis. |
| Figure 9 | Unplug all cable conn. from PCA. |
| Figure 10 | Release 6 pcs screws from PCA. |
| Figure 11 | Remove PCA from chassis |
| Figure 12 | Push the hooks on both sides and then pick up the memory |

PSG instructions for this template are available at [EL-MF877-01](#).
Figure 13 Unplug the cooler cable from PCA

Figure 14 Release 4 screws from cooler and remove it

Figure 15 Remove the battery from the PCA

Figure 16 Release the screw of the FIO cable

Figure 17 Push the plastic hook and rotation the FIO module inside. Remove the FIO module from chassis

Figure 18 Release the SD card reader screw

PSG instructions for this template are available at EL-MF877-01
Figure 19 Remove the SD Card reader from chassis

Figure 20 Release two screws of speaker

Figure 21 Remove the speaker from chassis

Figure 22 Release 4 pcs screws of PSU and remove it

Figure 23 Pull up the PSU and remove it

Figure 24 Cut the cable tie

PSG instructions for this template are available at EL-MF877-01
Figure 25 Remove screw for bottom

Figure 26 Remove screw for top

Figure 27 Remove FG screw

Figure 28 Disconnect fan connector

Figure 29 Cut the cable tie

Figure 30 Remove LED
Figure 31: Remove plastic cover

Figure 32: Remove PCB screw

Figure 33: Remove AC inlet, select switch screw

Figure 34: Cut output cable, AC inlet wire, LED wire

Figure 35: Remove capacitors use solder iron

Figure 36: Heat the solder of Electrolytic Capacitors greater than 2.5cm in diameter or height and remove it. (Crasto-S 180W E-Star-Acbel)
Figure 37 Heat the solder of Electrolytic Capacitors greater than 2.5cm in diameter or height and remove it. (C801, C951) (Crasto-S 180W E*6 PSU-Delta)

Figure 38 Heat the solder of Electrolytic Capacitors greater than 2.5cm in diameter or height and remove it. (C801, C802, C951, C303) (Crasto-S 180W REG PSU-Delta)

Figure 39 Heat the solder of Electrolytic Capacitors greater than 2.5cm in diameter or height and remove it. (Crasto-S 180W APFC-Acbel)

Figure 40 Heat the solder of Electrolytic Capacitors greater than 2.5cm in diameter or height and remove it. (Crasto-S 180W REG PSU-Chicony)

Figure 41 Heat the solder of Electrolytic Capacitors greater than 2.5cm in diameter or height and remove it. (Crasto-S 180W APFC PSU-Chicony)

PSG instructions for this template are available at EL-MF877-01